

# MBRE1060

Rev.G Oct.-2018

## 描述 / Descriptions

TO-277

TO-277 Plastic package Schottky diode .

## 特征 / Features

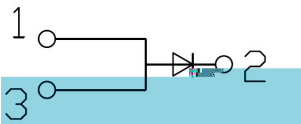
High Forward Surge Capability

High Forward Surge Capability, Low Forward Voltage Drop  $V_F(\text{typ})=0.32\text{V}$ , Excellent High Temperature Stability. HF Product.

## 用途 / Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

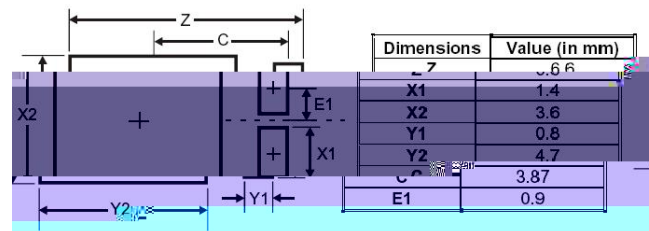
## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode



Suggested Pad layout

## 放大及印章代码 / h<sub>FE</sub> Classifications & Marking

See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	$V_{RRM}$ $V_{RWM}$ $V_{RM}$	60	V
RMS Reverse voltage	$V_{R(RMS)}$	42	V
Average Rectified Output Current	$I_O$	10	A
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	150	A
Junction Temperature Range	$T_{j MAX}$	150	
Storage Temperature Range	$T_{stg}$	-55 150	
Typical Thermal Resistance	$R_{\theta JA}$ Note 1	76	/W

**电性能参数 / Electrical Characteristics(Ta=25°C)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{BR}$	$I_R=0.5mA$	60			V
Forward voltage	$V_F$	$I_F=2A$ $T_J=25$		0.42	0.47	V
		$I_F=2A$ $T_J=125$		0.32		V
		$I_F=10A$ $T_J=25$		0.6	0.65	V
		$I_F=10A$ $T_J=125$		0.54		V
Instantaneous Reverse Current	$I_R$ Note 1	$V_R=60V$ $T_J=25$		50	100	$\mu A$
		$V_R=60V$ $T_J=100$			10	mA
		$V_R=60V$ $T_J=125$			50	mA

&Notes

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layout per.

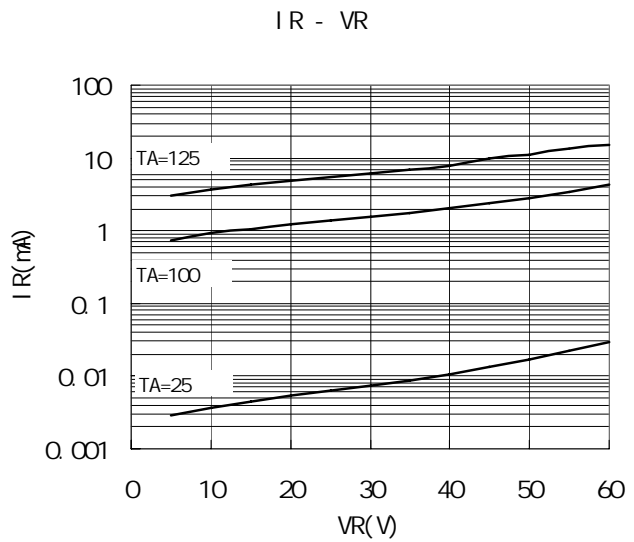
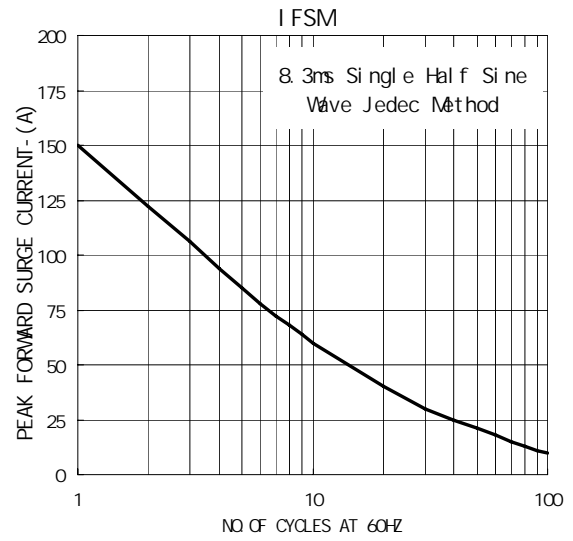
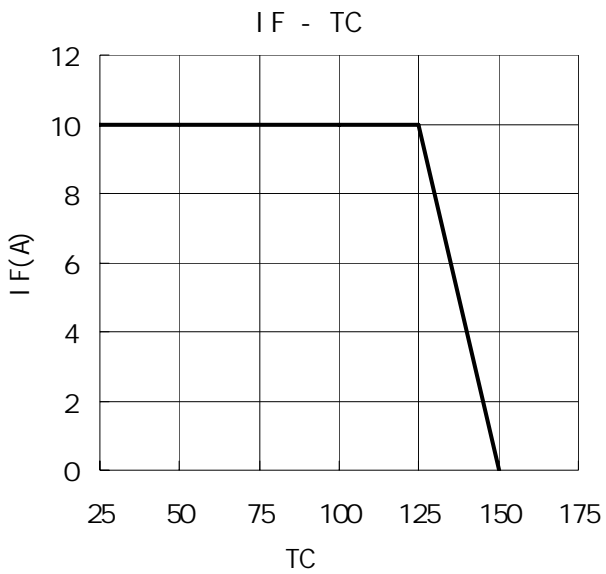
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effect.

/FR-4 PCB, 2oz. Copper, minimum recommended pad

&Short duration pulse test used to minimize self-heating

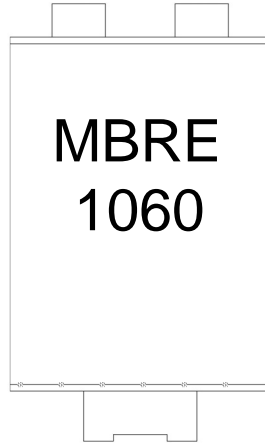
**电参数曲线图 / Electrical Characteristic Curve**



外形尺寸图 / Package Dimensions



**印章说明 / Marking Instructions**



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Note:

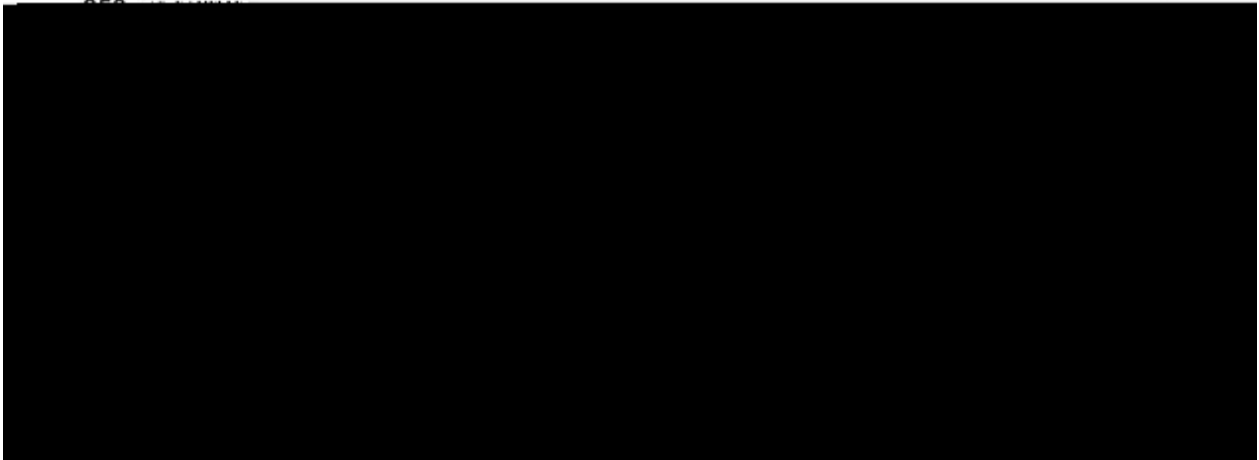
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Product Type.

\*\*\*\*:

Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



Note:

- |   |           |             |                                           |
|---|-----------|-------------|-------------------------------------------|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec.     |
| 2 | 245..5    | 5..0.5sec;  | 2.Peak Temp.:245..5 , Duration:5..0.5sec. |
| 3 | 2 ~ 10    | /sec.       | 3. Cooling Speed: 2~10 /sec.              |

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

260..5                      10..1 sec.                      Temp.:260±5                      Time:10±1 sec

**包装规格 / Packaging SPEC.**

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		

**使用说明 / Notices**